

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	762	scrib\$3 adj9 cut\$4 with laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 12:45
L5	143	scrib\$3 adj9 cut\$4 with laser with (mechanical\$5 blade)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 12:45
L6	88	scrib\$3 adj3 cut\$4 with laser with (mechanical\$5 blade)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 12:45
L7	0	scrib\$3 adj3 cut\$4 with laser with (mechanical\$5 blade) same cool\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 12:46
L8	5	scrib\$3 adj9 cut\$4 with laser with (mechanical\$5 blade) same cool\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 12:46
L9	20	scrib\$3 adj9 cut\$4 same laser same (mechanical\$5 blade) same cool\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 12:47
L10	15	9 not 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 12:47
L11	0	scrib\$3 adj5 subsequent \$5 adj5 cut\$4 with (mechanical\$5 blade)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 12:55
L12	0	scrib\$3 adj5 subsequent \$5 adj9 cut\$4 with (mechanical\$5 blade)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 12:55

L13	3	scrib\$3 adj5 subsequent \$5 with cut\$4 with (mechanical\$5 blade)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 12:56
L14	5	scrib\$3 adj5 subsequent \$5 with (sever\$4 cut\$4 break\$4 split\$5) with (mechanical\$5 blade)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 12:57
L15	2	14 not 13	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 12:57
L16	4	scrib\$3 adj5 subsequent \$5 with (sever\$4 cut\$4 break\$4 split\$5) same (mechanical\$5 blade) not 14 not 15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 12:58
L17	5	scrib\$3 adj5 subsequent \$5 with (sever\$4 cut\$4 break\$4 split\$5) with saw \$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 12:59
L18	2	scrib\$3 adj5 later with (sever\$4 cut\$4 break\$4 split\$5) with saw\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 13:02
L19	36	scrib\$3 adj5 complete\$4 adj4 (sever\$4 cut\$4 break \$4 split\$5) with (wafer semiconductor silicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 13:08
L20	34	scrib\$3 adj5 complete\$4 adj (sever\$4 cut\$4 break \$4 split\$5) with (wafer semiconductor silicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 13:08
L21	2	((("6669801") or ("6211488")).PN.	USPAT; USOCR	OR	OFF	2008/02/02 13:21
L22	2	"20010034564"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 13:39
L23	2	((("6562698") or ("6420245")).PN.	USPAT; USOCR	OR	OFF	2008/02/02 13:39

L24	4	22 23	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 13:39
L25	3	24 and scrib\$4 with cut\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 13:40
S1	552	dicing with laser with saw \$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 11:40
S2	147	S1 and (saw with (cutter blade))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/28 11:09
S3	48	S1 and (saw with (cutter blade)) and ((scrib\$4 with laser)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 10:40
S4	34	S1 and (saw with (cutter blade)) and ((scrib\$4 with laser) and ((saw\$4 cut cutting cutter blade) with (complet\$7 through))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 12:04
S5	5	S4 and yag	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/28 12:05
S7	2	"200075983"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:09
S8	1	("4983251").PN.	USPAT; USOCR	OR	OFF	2006/07/06 11:10
S9	12	"20020019069" "20020031864" "20020094607" "20020139577" "20030060034" "20030071335"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:10
S10	13	S8 S9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:11

S11	6	((("5952611") or ("6075710") or ("6087203") or ("6236107") or ("6365833") or ("6387729")).PN.	USPAT; USOCR	OR	OFF	2006/07/06 11:11
S12	18	"20010030357" "20020001882" "20020089043" "200201232" "20030071341"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:12
S13	24	S11 S12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:12
S14	37	S10 S13	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:12
S15	2	S14 and laser and saw	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:13
S16	0	S14 and (laser with scribe \$4) same ((saw \$3 mechanical \$3) with (nickel diamond cutting cut blade cutter))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:15
S17	0	S14 and (laser with scribe \$4) and ((saw \$3 mechanical \$3) with (nickel diamond cutting cut blade cutter))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:15
S18	2	S14 and (laser with (scribe \$4 etch \$4 cut cutter cutting street)) and ((saw \$3 mechanical \$3) with (nickel diamond cutting cut blade cutter saw))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:16
S19	707	(scribe \$4 with laser) same ((saw \$4 cut cutting cutter blade) with (scribe line))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:27
S20	31	(scribe \$4 with laser) same ((saw \$4 cut cutting cutter blade) with (scribe line)) same simultaneous \$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 12:41

S21	16	((scrib\$4 with laser) with ((saw\$4 cut cutting cutter blade) with (scribe line)) with (simultaneous\$4 "same time"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:48
S22	2	S21 not S20	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:53
S23	1	("6420245").PN.	USPAT; USOCR	OR	OFF	2006/07/06 11:53
S24	0	S23 and simultaneous\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:54
S25	1	S23 and (laser with (saw blade))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 12:26
S26	617	dicing with laser with saw \$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:59
S27	40	S26 and (saw with (cutter blade)) and (scrib\$4 with laser) and ((saw\$4 cut cutting cutter blade) with (complet\$7 through))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:59
S28	5	S27 and ((while during "same time" simultaneous \$4) with laser with (cut cutting sawing saw blade mechanical\$5))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:59
S29	2	S27 and (nickel with diamond)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 12:04
S30	55	S26 and (saw with (cutter blade)) and (scrib\$4 with laser)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 12:04
S31	2	S30 and (nickel with diamond)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 12:05

S32	9	wafer with (nickel with diamond with saw\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 12:12
S33	2	"20040188400"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 12:12
S34	1	S23 and ((while during "same time" simultaneous \$4) with (saw blade))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 12:26
S35	1	S23 and ((while during "same time" simultaneous \$4) with (laser))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 12:26
S36	707	(scrib\$4 with laser) same ((saw\$4 cut cutting cutter blade) with (scribe line))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 12:44
S37	5	S36 and (nickel with diamond)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 12:42
S38	74	S36 and (saw\$3 with diamond) not S37	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 12:46
S39	0	S36 and (saw\$3 with nickel with diamond) not S37	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 12:43
S40	0	S36 and (nickle with diamond) not S37	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 12:43
S41	2	S36 and (ni with diamond) not S37	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 12:43

S42	9	((scrib\$4 same laser) same ((saw\$4 cut cutting cutter blade) with (scribe line)) and ((ni nickel) with diamond)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 12:44
S43	43	S36 and wafer with (saw \$3 with diamond) not S37	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 12:46
S45	932	scrib\$4 with laser with (mechanical\$4 saw\$4 blade)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/01 13:21
S46	157	((scrib\$4 with laser with (mechanical\$4 saw\$4 blade)) same ((dice dicing) with (semiconductor silicon wafer integrated circuit))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/01 13:23
S47	4	S46 and ((mechanical\$4 saw\$4 blade) adj5 (follow \$3 subsequent prior before) adj5 (laser beam))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/01 13:26
S48	18	S46 and ((mechanical\$4 saw\$4 blade) near5 (follow \$3 subsequent prior before) near5 (laser beam))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/01 13:24
S49	14	S48 not S47	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/02 10:37
S50	1	("6737606").PN.	USPAT; USOCR	OR	OFF	2006/12/01 13:26
S51	244	laser with (deep\$4 depth penetrat\$4) with scrib\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/02 10:39
S52	32	S51 and (deep\$4 depth penetrat\$4) with micron	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/02 11:32
S53	2	"20040188400"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/02 11:17

S54	1	S53 and depth	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/02 11:17
S55	2	"20020086137"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:43
S56	2	S55 and saw\$4 near5 groove	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/02 11:32
S57	2	"20010034564"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:44
S58	1	("6562698").PN.	USPAT; USOCR	OR	OFF	2007/09/07 09:44
S59	0	("s23s55s57s58").PN.	USPAT; USOCR	OR	OFF	2007/09/07 11:41
S60	1	("6420245").PN.	USPAT; USOCR	OR	OFF	2007/09/07 11:41
S61	2	"20020086137"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 11:41
S62	2	"20010034564"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 11:41
S63	1	("6562698").PN.	USPAT; USOCR	OR	OFF	2007/09/08 09:18
S64	6	S60 S61 S62 S63	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 13:15
S65	4	S64 and micron	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:57

S66	0	S64 and (watts w) same (hz herze h)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 11:50
S67	4	S64 and (watts w)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 11:51
S68	0	S64 and hz	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 11:51
S69	35	laser with scrib\$4 and (laser power) with (watts w) with (hz hertz)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 11:55
S70	29	laser with scrib\$4 and (laser power) with (watts w) with (hz hertz) same (refresh rate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 11:57
S71	3	laser with scrib\$4 and (laser power) with (watts w) with (hz hertz) same refresh	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 11:58
S72	9	laser with scrib\$4 and (watts w) and (hz hertz) with refresh	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 11:59
S73	23	laser same (watts w) and laser same (hz hertz) with refresh	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:03
S74	50	laser with (power watts w) and laser with refresh near rate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:03
S75	20	laser with (power watts w) with ("100" "200" "300" "400" "500" "600" "700" "800" "900" "1000") and laser with refresh near rate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:24

S76	212	laser with (scrib\$4 etch\$4 cut cutting textur\$4 trim \$4) and (power watts w) with ("100" "200" "300" "400" "500" "600" "700" "800" "900" "1000") and refresh near rate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:24
S77	40	laser with (scrib\$4 etch\$4 cut cutting textur\$4 trim \$4) and (power watts w) with ("100" "200" "300" "400" "500" "600" "700" "800" "900" "1000") and refresh near rate with hz	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:15
S78	611194	"219"/\$.ccls. "438"/\$.ccls. "29"/\$.ccls. "156"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:12
S79	34657	S78 and (laser beam) same (scrib\$4 etch\$4 cut cutting textur\$4 trim\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:21
S80	8	S79 and (power watts w) with ("100" "200" "300" "400" "500" "600" "700" "800" "900" "1000") and refresh near rate with hz	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:16
S81	5650	S79 and (power watts w) with ("100" "200" "300" "400" "500" "600" "700" "800" "900" "1000") not S80	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:16
S82	3167	S79 and (power watts w) near2 ("100" "200" "300" "400" "500" "600" "700" "800" "900" "1000") not S80	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:22
S83	0	S82 and (refresh\$3 with hz)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:17
S84	15	S82 and refresh\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:17

S85	34836	S78 and (laser beam) same (peen\$4 scribe\$4 etch\$4 cut cutting texture\$4 trim\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:21
S86	3175	S85 and (power watts w) near2 ("100" "200" "300" "400" "500" "600" "700" "800" "900" "1000") not S80	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:22
S87	15	S86 and refresh\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:22
S88	4007	laser with (scribe\$4 etch\$4 cut cutting texture\$4 trim\$4) and laser with (power watts w) with ("100" "200" "300" "400" "500" "600" "700" "800" "900")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:24
S89	1750	laser with (scribe\$4 etch\$4 cut cutting texture\$4 trim\$4) and laser with (power watts w) near2 ("100" "200" "300" "400" "500" "600" "700" "800" "900")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:25
S90	66	laser with (scribe\$4 etch\$4 cut cutting texture\$4 trim\$4) and laser with (power watts w) near2 ("100" "200" "300" "400" "500" "600" "700" "800" "900") same (refresh\$4 cycle)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:31
S91	76	laser with (scribe\$4 etch\$4 cut cutting texture\$4 trim\$4) and laser with (power watts w) near2 ("100" "200" "300" "400" "500" "600" "700" "800" "900") same (refresh\$4 duty cycle)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:32
S92	76	laser with (scribe\$4 etch\$4 cut cutting texture\$4 trim\$4) and laser with (power watts w) near2 ("100" "200" "300" "400" "500" "600" "1000") same (refresh\$4 duty cycle)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:33

S93	27	laser with (scrib\$4 etch\$4 cut cutting textur\$4 trim \$4) same (power watts w) near2 ("100" "200" "300" "400" "500" "600" "1000") same (refresh\$4 duty cycle)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:35
S94	8	S93 and (laser scrib\$4 etch \$4 cut cutting textur\$4 trim\$4) with (silicon wafer semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:35
S95	0	S84 and nickel same diamond	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 13:09
S96	215	(saw blade) with nickel with diamond	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:58
S97	526	(saw sawed sawing blade cut cutter cutting) with nickel with diamond	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 12:59
S98	90	wafer same (saw sawed sawing blade cut cutter cutting) with nickel with diamond	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 13:01
S99	8	wafer same (saw sawed sawing blade cut cutter cutting) with nickel with diamond and (yag with laser)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 13:04
S100	8	wafer same (saw sawed sawing blade cut cutter cutting) with nickel with diamond and (yag and laser)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 13:04
S101	1	S84 and yag	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 13:23
S102	1	S84 and mm adj sec	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 13:12

S103	1	S64 and mm adj sec	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 13:23
S104	111	laser near2 scrib\$4 and mm adj sec	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 13:24
S105	43	wafer with saw\$3 with blade and mm adj sec	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 13:25
S106	27	wafer with saw\$3 with blade and (nickel diamond) with blade and mm adj sec	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 13:25
S107	2	((("6562698") or ("6420245")).PN.	USPAT; USOCR	OR	OFF	2007/09/08 09:34
S108	1	("3691707").PN.	USPAT; USOCR	OR	OFF	2007/09/08 09:34
S109	670	laser with (wafer silicon dielectric semiconduct\$4) with (dic\$3 etch\$4 cut\$4 groov\$4 ablat\$4 scrib\$4) with (liquid cool\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/31 12:29
S110	19429	cut\$4 with (saw\$4 mechanical\$5 blade knife knife) with (scrib\$4 street groov\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/31 12:31
S111	23	S109 and S110	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/31 12:31
S112	5	S109 and (cut\$4 saw\$4 mechanical\$5 blade knife knife) with (follow\$4 subsequent\$4) with (scrib \$4 street groov\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/31 12:33
S113	2	S112 and S110	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/31 12:33

S114	166	S109 and (dic\$3 etch\$4 cut\$4 groov\$4 ablat\$4 srib\$4) with (break\$4 crack\$4 sever\$4 saw\$4 blade)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/31 12:35
S115	72	S109 and (dic\$3 etch\$4 cut\$4 groov\$4 ablat\$4 srib\$4) with (break\$4 crack\$4 sever\$4 saw\$4 blade) with (cool\$4 liquid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/31 12:36
S116	18	S109 and (dic\$3 etch\$4 cut\$4 groov\$4 ablat\$4 srib\$4) with (break\$4 crack\$4 sever\$4 saw\$4 blade) with (follow\$4 subsequent\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/31 12:36
S117	673	laser with (pellet wafer silicon dielectric semiconduct\$4) with (dic \$3 etch\$4 cut\$4 groov\$4 ablat\$4 srib\$4) with (liquid cool\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/31 12:39
S118	1	("6737606").PN.	USPAT; USOCR	OR	OFF	2008/01/31 14:10
S119	29	S117 and srib\$4 with cool \$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/31 14:25

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